

Ausgewählte Publikationen

- Christian Schwarzer, Alexander Hensel; Frederik Roth; Joerg Franke; Michael Kaloudis, Investigation of Pressureless Sintered Interconnections on Plasma Based Additive Copper Metallization for 3-Dimensional Ceramic Substrates for Surface Acoustic Wave Sensors in High Temperature Applications, 2020 IEEE 70th Electronic Components and Technology Conference (ECTC) (2020)
- T. Sauer, S. Kefer, W. Ruppert, R. Hellmann und M. Kaloudis, Integration of Bragg grating sensors in components made of carbon fiber reinforced polymers, 20. GMA/ITG-Fachtagung Sensoren und Messsysteme 2019, pp. 806-810 (2019)
- Christian Schwarzer, Wolfgang Schmitt, Michael Schnepf, Jörg Franke, Michael Kaloudis, Investigation of a Sintering Process for Micro-Scale Copper Material – SMTA Electronic in Harsh Environments Conference, Amsterdam, Netherlands, 04.04.2019 (2019)
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- Christian Schwarzer, Dennis Fuchs, Michael Kaloudis, Miriam Rauer, Ping Xu, Jörg Franke, Andreas Krügelstein, Investigation of the Influence of Voids on the Reliability of Solder Joints by Finite Element Method - Date Published: 9/17/2017 Conference: SMTA International, Rosemont, IL, USA (2017)
- Schwarzer, Christian; Fuchs, Dennis, Rauer, Miriam, Lang, Kurt-Jürgen, Kruegelstein, Andreas; Franke, Joerg; Kaloudis, Michael, Investigation of the influence of voids on the reliability of LED solder joints by computer tomography and forward voltage measurement. In: 21st European Microelectronics and Packaging Conference & Exhibition. Warschau, 10.09.2017 - 13.09.2017 (2017)
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- Miriam Rauer, Antje Volkert, Timo Schreck, Stefan Härter, Michael Kaloudis; Computed-Tomography-Based Analysis of Voids in SnBi57Ag1 Solder Joints and Their Influence on the Reliability, *Journal of Failure Analysis and Prevention*; June 2014, Volume 14, Issue 3, pp 272-281 (2014)
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